Product Change Notification

Change Notification #: 115934 - 02

Change Title:

Intel® Ethernet Converged Network Adapter X520 - DA2, open optic, Product Code: EX520DA2G2P5, MM# 913120

Intel® Ethernet Converged Network Adapter X520 - SR2, Product Code: E10G42BFSRG1P5, MM# 901223, Product Code: E10G42BFSRBLK, MM# 927247, Product Code: E10G42BFSR, MM# 900137

Intel® Ethernet Converged Network Adapter X520 - SR1, Product Code: E10G41BFSRG1P5, MM# 901222, Product Code: E10G41BFSRBLK, MM# 927757, Product Code: E10G41BFSR, MM#900141

Intel® Ethernet Converged Network Adapter X520 - DA1, Product Code: E10G41BTDAG1P5, MM# 901226

Intel® Ethernet Converged Network Adapter X520 - DA2, Product Code: E10G42BTDAG1P5, MM# 901227, Product Code: E10G42BTDA, MM# 900139, Product Code: E10G42BTDABLK, MM# 927249

Intel® Ethernet Converged Network Adapter X520 - LR1, Product Code: E10G41BFLRBLK, MM# 927248, Product Code: E10G41BFLR,MM#900140

PCN 115934-02, Label,
Label Updates

Reason for Revision: Updated to correct revision number

Date of Publication: December 5, 2017

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 30, 2017

Description of Change to the Customer:

The Intel products listed in the Products Affected table will undergo the following changes:

1. The OUI Block 90-E2-BA has hit a low water mark, the new OUI Block used will be F8-F2-1E.

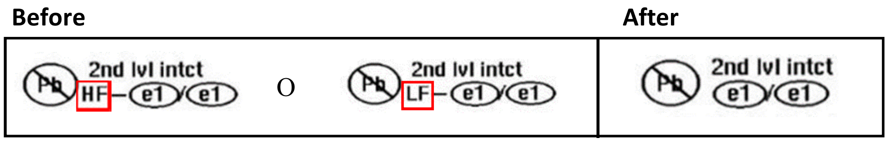
2. The Taiwan BSMI has a new RoHS declaration and inspection mark.
    - The BSMI logo will be updated on the board level, with a cover up label, and on the packaging label if it currently exists there.

Existing

New

3. Ukraine has a new RoHS declaration that will be added to the outer box packaging label.

4. In order to align all our products and labels with the JEDEC 609A Standard for board assembly marking, we will remove the HF or LF (as applicable) from all outer box packaging labels if it currently exists there.



5. As per the Intel Corporate Green Initiative, Intel is moving its products to a RoHS Compliant 100% lead-free process which impacted several of the flip-chip silicon product lines. The current silicon products are listed as 'exempt' based on the EU RoHS exemption for FLI leaded parts. This change removed that RoHS exemption. There is no impact on the silicon's function, electrical performance, mechanical use or stated reliability. Intel has qualified and certified this change in the same way as all products supplied to our customers. There is no form-fit-function change for any of the impacted silicon. FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology. There is no change to the second level interconnects for these products. This change affects First Level Interconnects only. The transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.

Niantic Eutectic (Pb-bumps)

Niantic Lead-free

As a result of these changes, the PBA (printed board assembly) and TA (top assembly) numbers will roll as noted in the affected products table within this PCN. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.
The customer can expect to receive mixed inventory.
Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
E10G42BFSR	900137	E68788-008	E68785-008	E68788-009	E68785-009
E10G42BTDA	900139	E68797-007	E68793-007	E68797-008	E68793-008
E10G41BFLR	900140	E65557-008	E66561-009	E65557-009	E66561-010
E10G41BFSR	900141	E68795-008	E68787-008	E68795-009	E68787-009
E10G41BFSRG1P5	901222	E58748-007	E66593-009	E58748-008	E66593-010
E10G42BFSRG1P5	901223	E58747-008	E70854-009	E58747-009	E70854-010
E10G41BTDAG1P5	901226	G30772-005	G30771-005	G30772-006	G30771-006
E10G42BTDAG1P5	901227	E64797-006	E66560-007	E64797-007	E66560-008
EX520DA2G2P5	913120	G24942-005	G24940-006	G24942-006	G24940-007
E10G42BFSRBLK	927247	G90056-002	E68785-008	G90056-003	E68785-009
E10G41BFLRBLK	927248	G90054-002	E66561-009	G90054-003	E66561-010
E10G42BTDABLK	927249	G90047-002	E68793-007	G90047-003	E68793-008
E10G41BFSRBLK	927757	G90055-002	E68787-008	G90055-003	E68787-009

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 21, 2017	00	Originally Published PCN
December 2, 2017	01	Added correct Products Affected table with TA and PBA rolls and updated Milestones date
December 5, 2017	02	Updated to correct revision number

Product Change Notification
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
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